

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT3075648

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
JI EUN PARK	10/18/2014
KYUN HA BAN	10/18/2014
JA YOON KIM	10/18/2014
CHANG MIN HONG	10/18/2014
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SAMSUNG SDI CO., LTD.
<b>Street Address:</b>	150-20 GONGSE-RO
<b>Internal Address:</b>	GIHEUNG-GU
<b>City:</b>	YONGIN-SI
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>Postal Code:</b>	446-902
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	14520449
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(704)945-6735
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	704-945-6700
<b>Email:</b>	docket@ahpapatent.com
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<b>ATTORNEY DOCKET NUMBER:</b>	7250.010
<b>NAME OF SUBMITTER:</b>	MELISSA B. PENDLETON
<b>SIGNATURE:</b>	/Melissa B. Pendleton/
<b>DATE SIGNED:</b>	10/22/2014
<b>Total Attachments: 4</b> source=AssignmentUSPTO#page1.tif	

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### RECORDATION FORM COVER SHEET PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

**1. Name of conveying party(ies)**  
JI EUN PARK  
KYUN HA BAN  
JA YOON KIM  
CHANG MIN HONG  
Additional name(s) of conveying party(ies) attached?  Yes  No

**2. Name and address of receiving party(ies)**  
Name: Samsung SDI Co., Ltd.  
Internal Address: \_\_\_\_\_  
\_\_\_\_\_

**3. Nature of conveyance/Execution Date(s):**  
Execution Date(s) October 18, 2014  
 Assignment  Merger  
 Security Agreement  Change of Name  
 Joint Research Agreement  
 Government Interest Assignment  
 Executive Order 9424, Confirmatory License  
 Other \_\_\_\_\_

Street Address: 150-20 Gongse-ro, Giheung-gu  
\_\_\_\_\_ City: Yongin-si  
State: Gyeonggi-do  
Country: South Korea Zip: \_\_\_\_\_  
Additional name(s) & address(es) attached?  Yes  No

**4. Application or patent number(s):**  This document is being filed together with a new application.  
A. Patent Application No.(s)  
14/520,449  
B. Patent No.(s)  
\_\_\_\_\_

Additional numbers attached?  Yes  No

**5. Name and address to whom correspondence concerning document should be mailed:**  
Name: Additon, Higgins & Pendleton, P.A.  
Internal Address: \_\_\_\_\_  
\_\_\_\_\_ Street Address: 11610 N. Community House Road, Suite 200  
City: Charlotte  
State: NC Zip: 28277-2199  
Phone Number: 704-945-6700  
Fax Number: 704-945-6735  
Email Address: \_\_\_\_\_

**6. Total number of applications and patents involved:** 1  
**7. Total fee (37 CFR 1.21(h) & 3.41) \$** \_\_\_\_\_  
 Authorized to be charged by credit card  
 Authorized to be charged to deposit account  
 Enclosed  
 None required (government interest not affecting title)

**8. Payment Information**  
a. Credit Card Last 4 Numbers \_\_\_\_\_  
Expiration Date \_\_\_\_\_  
b. Deposit Account Number \_\_\_\_\_  
Authorized User Name \_\_\_\_\_

**9. Signature:** /Melissa B. Pendleton/ October 22, 2014  
Signature Date  
Melissa B. Pendleton  
Name of Person Signing  
Total number of pages including cover sheet, attachments, and documents: 4

Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to:  
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O. Box 1450, Alexandria, V.A. 22313-1450

## ASSIGNMENT

WHEREAS, I, **Ji Eun PARK**, a Korean citizen, with a mailing address of 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Kyun Ha BAN**, a Korean citizen, with a mailing address of 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Ja Yoon KIM**, a Korean citizen, with a mailing address of 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; and **Chang Min HONG**, a Korean citizen, with a mailing address of 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea (hereinafter referred to as "ASSIGNOR"), am a joint inventor of certain new and useful improvements (hereinafter collectively referred to as "INVENTION") in *Thermoplastic Resin Composition Having Improved Weather Resistance*, for which an application for United States Letters Patent is being filed concurrently herewith and which application claims priority from a Korean application filed on October 30, 2013, under Serial No. 10-2013-0130314, all applications listed above being hereinafter referred to as the "APPLICATION"; and

WHEREAS, Samsung SDI Co., Ltd., a Korean corporation (hereinafter referred to as "ASSIGNEE"), having a principal place of business at 150-20, Gongse-ro, Giheung-gu, Yongin-si, Gyeonggi-do 446-577, Republic of Korea, has acquired the equitable right, title, and interest—and is desirous of acquiring any remaining right, title, and interest—in and to said INVENTION as described in said APPLICATION, and in and to any and all Letters Patent that shall be granted with respect to said INVENTION in the United States of America and all foreign countries;

NOW, THEREFORE, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I, the ASSIGNOR, have sold, assigned, transferred, and conveyed unto said ASSIGNEE, its successors and assigns, my equitable right, title, and interest—and by these presents do

hereby sell, assign, transfer, and convey unto said ASSIGNEE, its successors and assigns any remaining right, title, and interest— in and to said INVENTION and APPLICATION, in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues, reexaminations, or extensions thereof that may be granted therefore or thereon, for the full term for which said Letters Patent may be granted, together with the right to claim the priority of said APPLICATION in all foreign countries in accordance with international treaties and conventions, the same to be held and enjoyed by said ASSIGNEE, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by me if an assignment and sale had not been made.

I acknowledge that at the time the INVENTION was made, the INVENTION was subject to an obligation of assignment to said ASSIGNEE. I further acknowledge that said ASSIGNEE has the sole right to determine patent prosecution strategies with respect to said INVENTION and all corresponding applications, and hereby request that Letters Patent be issued in accordance with this assignment.

I further covenant and agree to bind my heirs, legal representatives, and assigns, promptly to communicate to said ASSIGNEE or its representatives any facts known to me relating to said INVENTION, to testify in any interference or legal proceedings involving said INVENTION, to execute any additional papers that may be requested to confirm the right of the ASSIGNEE, its representatives, successors or assigns to secure patent or similar protection for said INVENTION in all countries and to vest in the ASSIGNEE complete title to said INVENTION and Letters Patent, without further compensation, but at the expense of said ASSIGNEE, its successors, assigns and other legal representatives.

As the below named inventor, I hereby declare:

The application for United States Letters Patent being filed concurrently herewith was made or authorized to be made by me.

I believe that I am the original or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in the declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

IN WITNESS WHEREOF, I have hereunto signed my name on the day and year set forth below.

<u>Oct 18</u> , 2014	<u>박지은</u> Ji Eun PARK
<u>Oct 16</u> , 2014	<u>반주하</u> Kyun Ha BAN
<u>Oct 16</u> , 2014	<u>김윤</u> Ja Yoon KIM
<u>Oct 18</u> , 2014	<u>홍기민</u> Chang Min HONG